



RABIN & CHAMPAGNE, P.C.

08-19-1998



100796636

STEVEN M. RABIN
THOMAS M. CHAMPAGNE*
ROBERT H. BERDO, JR.

SUITE 1111
1725 K STREET, N.W.
WASHINGTON, D.C. 20006

PATENT, TRADEMARK
AND COPYRIGHT LAW
TELEPHONE: (202) 659-1915
TELEFAX: (202) 659-1898
E-MAIL: rabinlaw@aol.com

*ADMITTED TO A BAR OTHER THAN D.C.

MRD 7.14.98

RECORDATION COVER SHEET - PATENT APPLICATION

NAME OF CONVEYING PARTY : Tung-Po CHEN, Hong-Tsz PAN
And Wen-Yi Hsieh

NAME OF RECEIVING PARTY : United Microelectronics Corp.

ADDRESS OF RECEIVING PARTY : No. 3, Li-Hsin Rd. II, Science-Based
Industrial Park, Hsinchu, Taiwan, R.O.C.

NATURE OF CONVEYANCE : Assignment of U.S. patent application

CONVEYANCE EXECUTION DATE : May 22 and 25, 1998

PATENT APPLICATION NO. : 09/073,861

APPLICATION FILED TOGETHER
WITH THIS DOCUMENT : NO

APPLICATION EXECUTION DATE : May 22 and 25, 1998

CORRESPONDENCE
ADDRESS : RABIN & CHAMPAGNE, P.C.
1725 K Street, N.W., Suite 1111
Washington, D.C. 20006

ATTORNEY REFERENCE : JIA 449

TOTAL NUMBER OF PATENTS
AND APPLICATIONS INVOLVED : One

TOTAL FEE PAID : \$40.00 **E**

METHOD OF PAYMENT : Enclosed
 Authorized to be charged to
deposit account

In the event there is attached hereto no check, or a check for an insufficient amount, please charge the fee to our Account No. 18-0002 and notify us accordingly.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

07/21/1998 JARTIS 00000054 09073861

03 FC:581

Steven M. Rabin
(Registration No. 29,102)

7/14/98
Date

SMR/dmb

Total number of pages including cover sheet, attachments and document: 3

ASSIGNMENT

WHEREAS, (1) Tung-Po Chen (2) Hong-Tsz Pan
(3) Wen-Yi Hsieh

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: SALICIDE FORMATION PROCESS

Filed: May 7, 1998

Serial No.: Not Assigned

Executed concurrently with the execution of this instrument

WHEREAS, United Microelectronics Corp., of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Tung-Po Chen
Signature

May 25, 1998
date

Hong-loy Pan
Signature

May 25, 1998
date

Wen-Yi Hsieh
Signature

May 22, 1998
date

Signature

date